



Material Content Data Sheet



Sales Product Name		BGB 741L7ESD E6327		Issued		31. July 2018		
MA#		MA001789546						
Package		PG-TSLP-7-1		Weight*		1.59 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.002	0.11		1085	
	noble metal	gold	7440-57-5	0.007	0.42		4209	
	inorganic material	silicon	7440-21-3	0.059	3.71	4.24	37059	42353
leadframe	non noble metal	nickel	7440-02-0	0.329	20.74	20.74	207432	207432
	noble metal	gold	7440-57-5	0.046	2.89	2.89	28855	28855
encapsulation	inorganic material	antimonytrioxide	1309-64-4	0.001	0.03		338	
	organic material	carbon black	1333-86-4	0.011	0.68		6752	
	plastics	epoxy resin	-	0.144	9.12		91156	
	inorganic material	silicondioxide	60676-86-0	0.915	57.68	67.51	576986	675232
leadfinish	noble metal	gold	7440-57-5	0.032	2.00	2.00	19960	19960
plating	noble metal	palladium	7440-05-3	0.010	0.62		6208	
	noble metal	gold	7440-57-5	0.032	2.00	2.62	19960	26168
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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